

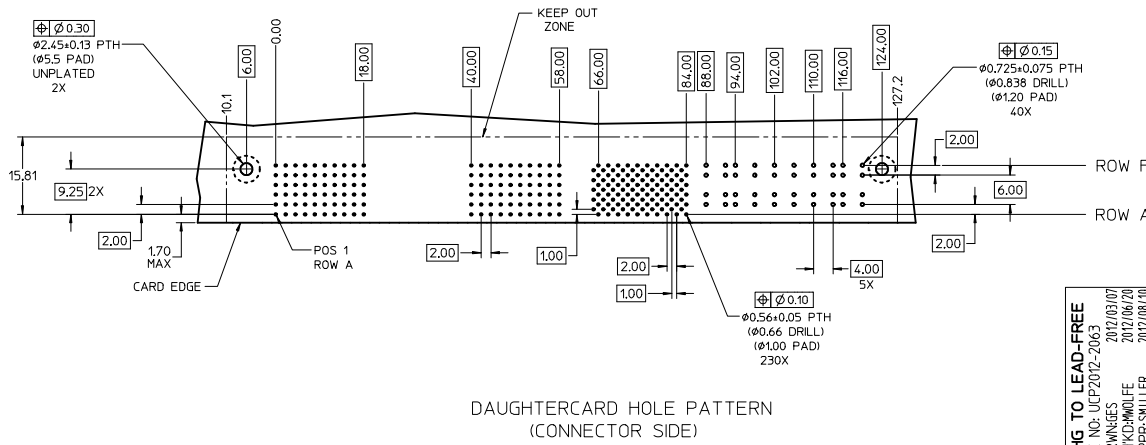
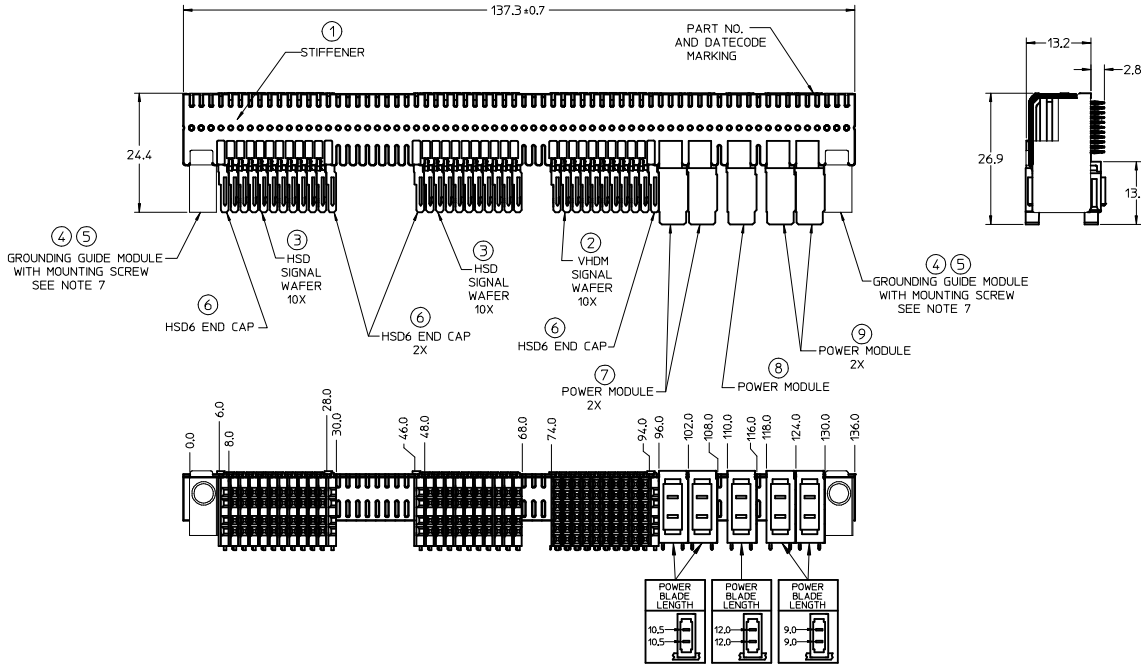
CUSTOMER: BROADBUS TECHNOLOGIES

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP)
GLASS-FILLED, UL94V-0, BLACK
TERMINALS - HIGH PERFORMANCE COPPER ALLOY
STIFFENER - STAINLESS STEEL
2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA,
0.76 MICROMETERS MINIMUM THICKNESS; SELECTIVE
MATTE TIN (Sn) ON PCB TAILS,
NICKEL (Ni) UNDERPLATE OVERALL.
3. REFER TO MOLEX PRODUCT SPECIFICATION PS-74031-999 FOR
PERFORMANCE SPECIFICATIONS.
4. REFER TO MOLEX DOCUMENT SD-74031-002 FOR ADDITIONAL
DETAIL ON THE VHDM SIGNAL WAFER.
5. REFER TO MOLEX DOCUMENT SD-74881-002 FOR ADDITIONAL
DETAIL ON THE HSD SIGNAL WAFER.
6. REFER TO MOLEX DOCUMENT SD-75885-001 FOR ADDITIONAL
DETAIL ON THE POWER MODULE.
7. MOUNTING SCREWS WILL BE BAGGED WITH EACH CONNECTOR.
8. PARTS ARE PACKAGED IN TUBES PER PK-70873-5040.
9. REFER TO MOLEX DOCUMENT SD-74039-028 FOR ADDITIONAL
DETAIL ON THE GROUNDED GUIDE MODULE.
10. THIS PART CONFORMS TO CLASS 'B' REQUIREMENT OF MOLEX
COSMETIC SPECIFICATION PS-45499-002.

LEAD-FREE
PLATING

ITEM	PART NUMBER	DESCRIPTION	QTY
1	74036-0137	STIFFENER	1
2	74031-1001	SIGNAL WAFER - VHDM6, LF	10
3	74881-1001	SIGNAL WAFER - HSD6, LF	20
4	74039-6816	GROUNDED GUIDE MODULE	2
5	73774-0000	GRND/JOINER MNTG SCREW	2
6	74888-0001	END CAP - HSD6	4
7	75885-6330	POWER MODULE, LF	2
8	75885-6440	POWER MODULE, LF	1
9	75885-6220	POWER MODULE, LF	2



CHG TO LEAD-FREE IEC NO: UICP2012-2063 DRAWN BY: CHYK-WOLFE CHECKED BY: APPROX-MILLER DATE: 2012/03/07 DATE: 2012/06/20 DATE: 2012/08/10	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm	MM ONLY	1:1	METRIC	☉
	▽=0	INCH				
	▽=0					
		ANGULAR ±1/2°	MATERIAL NO.	DOCUMENT NO.	TITLE	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	74886-0016	SD-74886-016	6 ROW HSD HYBRID, LF DAUGHTERCARD SALES DRAWING	
			SIZE D		molex	
					SHEET NO. 1 OF 1	